EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	492	(semi adj cured semicured semi-cured)same (cut dice separated)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/30 08:14
L2	449	1 and cured	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/30 11:14
L3	459	1 and (second again cured)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/30 08:16
L4	0	1 and (second with again with cured)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/30 08:15
L5	11	1 and (second same again same cured)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/30 08:15
L6	84	PREPREG AND (B ADJ STAGE SAME (CUT DICE DICING DICED SAW)) AND (SEMICONDUCTOR CHIP DIE)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/30 11:19
L7	30	PREPREG AND (B ADJ STAGE WITH (CUT DICE DICING DICED SAW)) AND (SEMICONDUCTOR CHIP DIE)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/30 11:19
L8	128	(B ADJ STAGE WITH (CUT DICE DICING DICED SAW)) AND (SEMICONDUCTOR CHIP DIE)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/30 12:35

EAST Search History

L10	0	b adj stageable with sheet and (semiconductor chip die)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/30 14:59
L11	473	b adj stage with sheet and (semiconductor chip die)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/30 16:28
L12	278	bum adj through	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/30 16:29
L13	1	bum adj through and b adj stage	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/30 16:30
L14	1	bum adj through and b adj stageable	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/30 16:30
L15	3	burn adj through and b adj stageable	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/30 16:31
L16	17	burn adj through and b adj stage	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/30 16:32
L17	5	push adj through and b adj stage	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/30 16:32

EAST Search History

S1	2	("20040198023").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/08/30 14:58
S2	4	(("6064114") or ("5977641")).PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/08/29 15:08
S3	248	(heal prevent reduce fix repair) with (crack or delamination) same (protecive encapsulent encapsulate encapsulating protecing)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/29 12:42
S4	2102	partial adj cure	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/29 12:42
S5	16481	S3 adn S4	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/29 12:41
S6	1	S3 and S4	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/29 12:41
S7	3751	partially adj cure	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/29 12:42
S8	0	S3 and S7	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/29 12:42

EAST Search History

S9	1523	(crack or delamination) same (protecive encapsulent encapsulate encapsulating protecing)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/29 12:42
S10	3	S7 and S9	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/29 12:48
S11	2474	(crack delamination) same (dicing cutting scriving separating) and semiconductor	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/29 12:49
S12	4678	(crack delamination) same (dice dicing cutting scribing scribe cut separate separating) and semiconductor	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/29 14:18
S13	44848	(crack delamination) same (dice dicing cutting scribing scribe cut separate separating)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/29 14:18
S14	89998	(crack delamination defect) same (dice dicing cutting scribing scribe cut separate separating)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/29 15:36
S15	4039166	resin epoxy encapsulant protective coating	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/29 14:21
S16	13991	S14 same S15	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/29 14:21

EAST Search History

S17	9194905	(repair mend fix bushel doctor furbish up, restore touch adj on better improve amend ameliorate meliorate)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/29 14:26
S18	9202203	(repair mend fix bushel doctor furbish up, restore touch adj on better improve amend ameliorate meliorate heal)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/29 14:26
S19	5235	S16 same S18	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/29 14:27
S20	351	S19 and semiconductor	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/29 14:27
S21	105080	(cur$3 or harden$3) with polymer	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/29 15:27
S22	30	S20 and S21	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/29 15:09
S23	1	("6885108").URPN.	USPAT	OR	ON	2006/08/29 15:19

EAST Search History

S24	54	("20020066966" | "20020098623" | "20020171177" | "20020182782" | "20030003180" | "20030003380" | "20030003405" | "20030043360" | "20030068584" | "20030072926" | "20030077418" | "20030089999" | "20030092220" | "20030093173" | "20030102566" | "20030129787" | "20030151167" | "20030201531" | "20030203158" | "20030207213" | "3978578" | "4033027" | "5157001" | "5462636" | "5682065" | "5742094" | "5933713" | "5956605" | "5977641" | "6210993" | "6251488" | "6259962" | "6268584" | "6326698" | "6337122" | "6353267" | "6391251" | "6399178" | "6432752" | "6482576" | "6489007" | "6514798" | "6524346" | "6544821" | "6544902" | "6549821" | "6562278" | "6562647" | "6585927" | "6593171" | "6620731" | "6635333" | "6849524" | "6885108").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/08/29 15:26
S25	23968	(recur$3 re-cur$3 re adj cur$3 or re adj harden$3 re-harden$3 reharden$3 harden$3) with polymer	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/29 15:34
S26	4854	b-stage b-stagable	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/29 15:29
S27	116	S25 and S26	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/29 15:29
S28	841	(recur$3 re-cur$3 re adj cur$3 or re adj harden$3 re-harden$3 reharden$3) with polymer	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/29 15:40

S29	7	S26 and S28	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/29 15:34
S30	16	S14 and S28	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/29 15:36
S31	0	S28 and (dice dicing)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/29 15:40
S32	44	cured after diced	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	WITH	ON	2006/08/29 15:54
S33	2	semi adj cured diced	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	WITH	ON	2006/08/29 15:55
S34	0	semi adj cure diced	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	WITH	ON	2006/08/29 15:55
S35	3504	semi adj cured	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	WITH	ON	2006/08/29 15:55
S36	0	semi adj cured (cut dice separated)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	WITH	ON	2006/08/29 15:55